



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

arlight

ARL-5730D21W-S 0.5W White



Features

- PLCC-2 package
- Extremely wide viewing angle
- Suitable for all SMT assembly and solder process
- Available on tape and reel
- Moisture sensitivity level: Level 4
- RoHS compliant

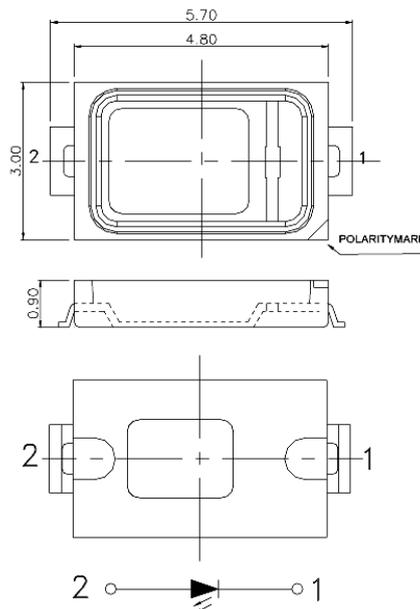
Description

- The White LED which was fabricated using a blue chip and the phosphor

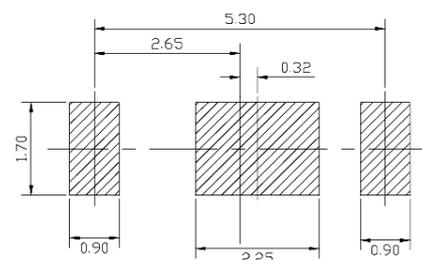
Application

- Lighting
- Backlight for TV

Package Dimensions



Recommended Soldering Pattern



1. All dimension units are millimeters.
2. All dimension tolerance is $\pm 0.15\text{mm}$ unless otherwise noted.

Part No.	Dice	Lens Type	Luminous intensity (mcd) @ 150mA		Luminous flux (lm) @ 150mA		Viewing Angle
			Min.	Max.	Min	Typ	
ARL-5730D21W-S 0.5W White	WHITE (InGaN)	Yellow Diffused	10 000	11 500	Min	Typ	2 θ 1/2
					30	35	120°

- Notes
1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
 2. The above luminous intensity measurement allowance tolerance $\pm 10\%$.

Electrical / Optical Characteristics at Ta=25°C

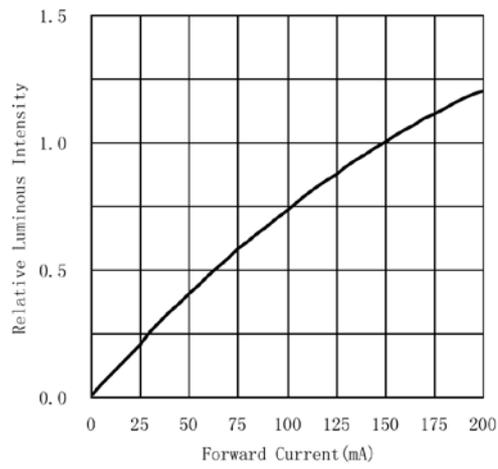
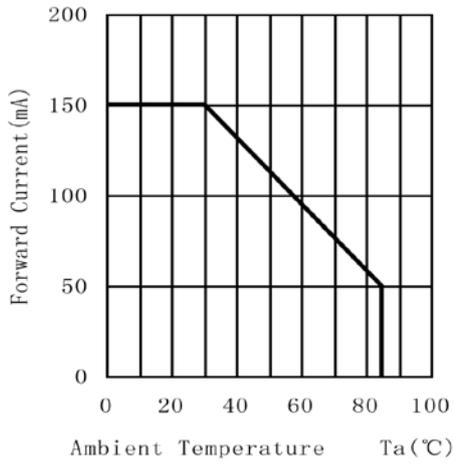
Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Forward Voltage	V_F	3.0	--	4.0	V	IF=150mA
Reverse Current	I_R	--	--	10	μA	VR = 5V
Color Coordinates	X	--	0.32	--	--	IF=150mA
	Y	--	0.33	--	--	IF=150mA
Color Temperature	Tc	--	6000	--	K	IF=150mA
Color Rendering Index	CRI	65	--	--	Ra	IF=150mA

Absolute Maximum Rating at Ta=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	Pd	500	mW
DC Forward Current	IF	150	mA
Peak Forward Current [1]	IFP	200	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C

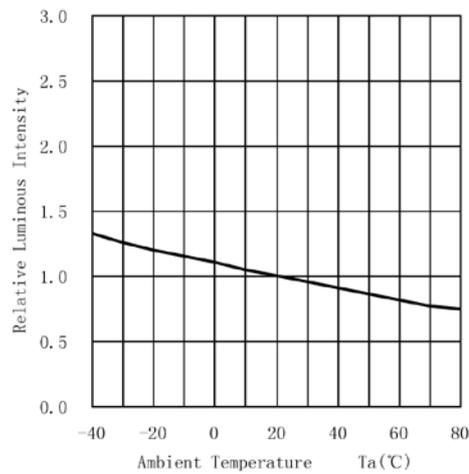
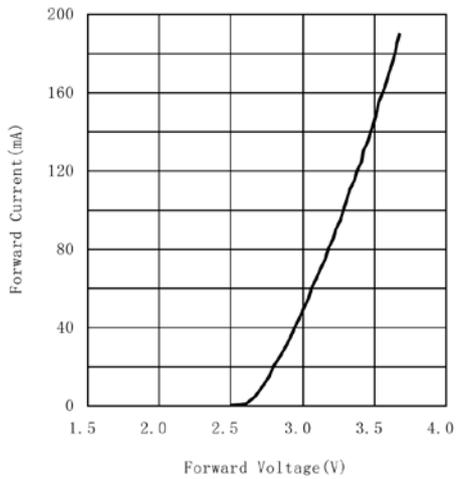
- Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

Typical optical characteristics curves



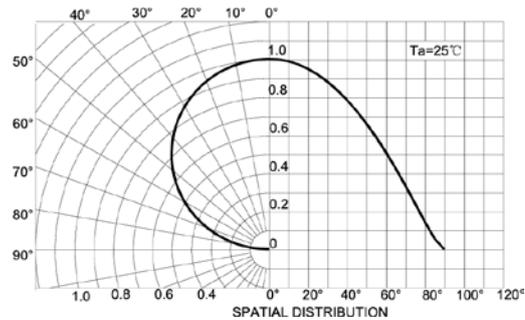
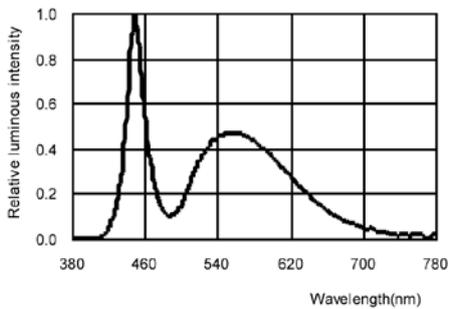
Forward Voltage VS. Forward Current

Ambient Temperature VS. Relative Intensity

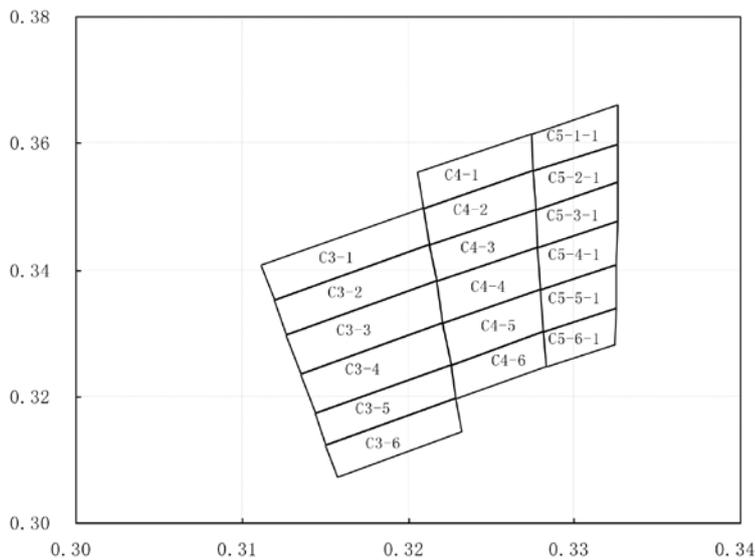


Relative spectral emission

Diagram characteristics of radiation



CIE Chromaticity Diagram



C3-1 6000-6500K				
X	0.3112	0.3209	0.3213	0.3120
Y	0.3408	0.3498	0.3440	0.3354

C3-2 6000-6500K				
X	0.3120	0.3213	0.3217	0.3127
Y	0.3354	0.3440	0.3382	0.3299

C3-3 6000-6500K				
X	0.3127	0.3217	0.3221	0.3136
Y	0.3299	0.3382	0.3317	0.3237

C3-4 6000-6500K				
X	0.3136	0.3221	0.3226	0.3144
Y	0.3237	0.3317	0.3251	0.3174

C3-5 6000-6500K				
X	0.3144	0.3226	0.3229	0.3151
Y	0.3174	0.3251	0.3198	0.3124

C3-6 6000-6500K				
X	0.3151	0.3229	0.3232	0.3157
Y	0.3124	0.3198	0.3145	0.3074

C4-1 5700-6000K				
X	0.3206	0.3274	0.3275	0.3209
Y	0.3554	0.3615	0.3556	0.3498

C4-2 5700-6000K				
X	0.3209	0.3275	0.3277	0.3213
Y	0.3498	0.3556	0.3496	0.3440

C4-3 5700-6000K				
X	0.3213	0.3277	0.3278	0.3217
Y	0.3440	0.3496	0.3436	0.3382

C4-4 5700-6000K				
X	0.3217	0.3178	0.3280	0.3221
Y	0.3382	0.3436	0.3369	0.3317

C4-5 5700-6000K				
X	0.3221	0.3280	0.3281	0.3226
Y	0.3317	0.3369	0.3302	0.3251

C4-6 5700-6000K				
X	0.3226	0.3281	0.3283	0.3229
Y	0.3251	0.3302	0.3247	0.3198

C5-1-1 5500-5700K				
X	0.3274	0.3326	0.3326	0.3275
Y	0.3615	0.3660	0.3599	0.3556

C5-1-2 5500-5700K				
X	0.3275	0.3326	0.3326	0.3277
Y	0.3556	0.3599	0.3538	0.3496

C5-3-1 5500-5700K				
X	0.3277	0.3326	0.3326	0.3278
Y	0.3496	0.3538	0.3477	0.3436

C5-4-1 5500-5700K				
X	0.3278	0.3326	0.3325	0.3280
Y	0.3436	0.3477	0.3409	0.3369

C5-5-1 5500-5700K				
X	0.3280	0.3325	0.3325	0.3281
Y	0.3369	0.3409	0.3340	0.3302

C5-6-1 5500-5700K				
X	0.3281	0.3325	0.3324	0.3283
Y	0.3302	0.3340	0.3283	0.3247

Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level :90%

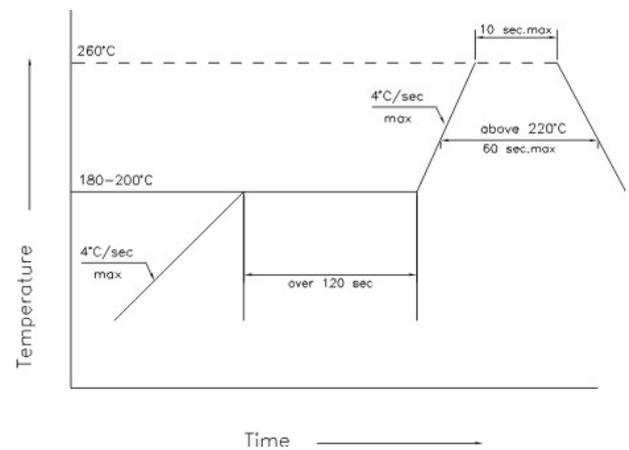
LTPD :10%

No.	Items	Ref.Standard	Test Condition	Test Hours/ Cycles	Sample Size	Ac/ Re
1	Reflow	JESD22-B106	Temp: 260°C max T=10 sec	3 times.	22Pcs.	0/1
2	Temperature Cycle	JESD22-A104	100°C±5°C 30 min. 5 min. -40°C±5°C 30 min.	100 Cycles	22Pcs.	0/1
3	Thermal Shock	JESD22-A106	100°C±5°C 5 min. -40°C ±5°C 5 min.	100 Cycles	22Pcs.	0/1
4	High Temperature Storage	JESD22-A103	Temp: 100°C±5°C	1000Hrs.	22Pcs.	0/1
5	Low Temperature Storage	JESD22-A119	Temp: -40°C±5v	1000Hrs.	22Pcs.	0/1
6	DC Operating Life	JESD22-A108	Ta=25°C±5°C IF=150mA	1000Hrs.	22Pcs.	0/1
7	High Temperature High Humidity	JESD22-A101	85°C±5°C/ 85%RH IF=50mA	1000Hrs.	22Pcs.	0/1

*The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

SMT Reflow Soldering Instructions

1. Reflow soldering should not be done more than two times
2. When soldering, do not put stress on the LEDs during heating

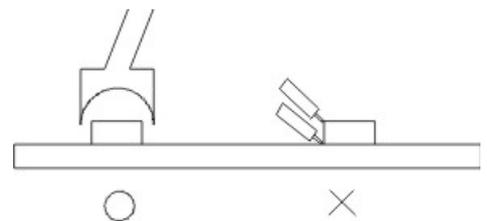


Soldering iron

1. When hand soldering, the temperature of the iron must be less than 300°C for 3 seconds
2. The hand solder should be done only one time

Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.



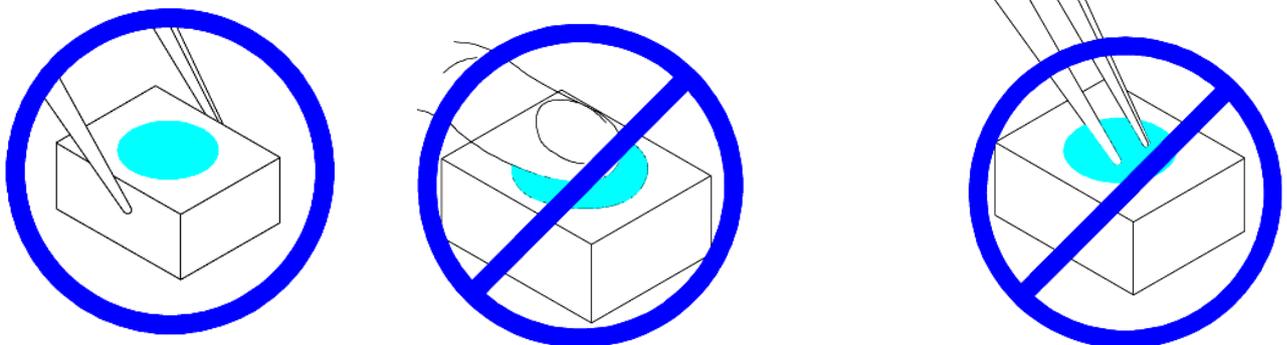
Cautions

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of the package. The pressure to the top surface will influence the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.

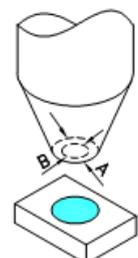
Handling Precautions

Compared to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although this characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

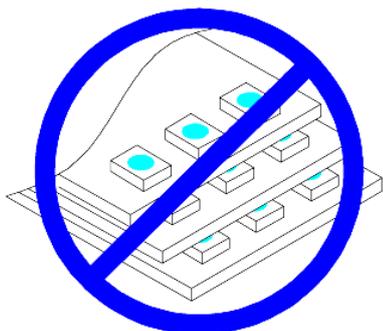
1. Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or handle the silicone lens surface, it may damage the internal circuitry.



2. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. The dimensions of the component must be accurately programmed in the pick-and-place machine to ensure precise pickup and avoid damage during production.



3. Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry

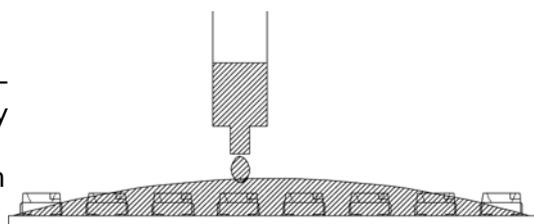


4. Not available in the situation of acidity for PH



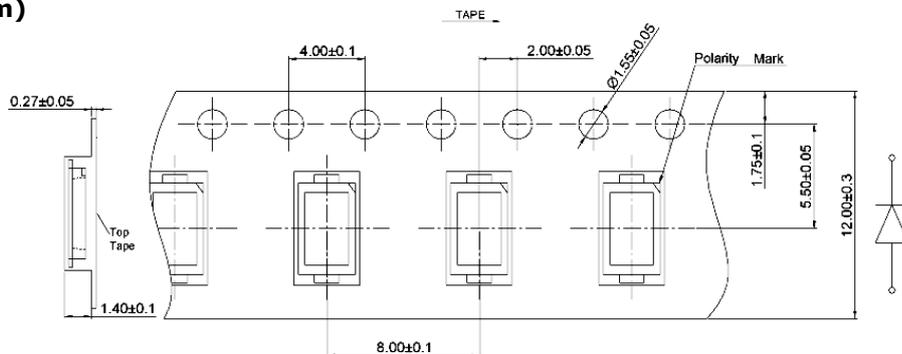
5. LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating.

6. When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally, as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external glue of the application products is required to be less than 1500PPM.

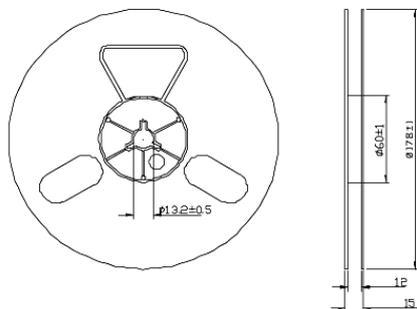


7. Other points for attention, please refer to our LED user manual.

Tape Specifications (Units : mm)



Moisture Resistant Packaging



Reel Dimensions

